Title (en)

ELECTRONIC, IN PARTICULAR MICROELECTRONIC, FUNCTIONAL GROUP AND METHOD FOR ITS PRODUCTION

Title (de)

ELEKTRONISCHE, INSBESONDERE MIKROELEKTRONISCHE FUNKTIONSGRUPPE UND VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)

GROUPE FONCTIONNEL ÉLECTRONIQUE, EN PARTICULIER MICROÉLECTRONIQUE, ET SON PROCÉDÉ DE FABRICATION

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2008061554A1] The invention relates to an electronic, in particular microelectronic, functional group and to a method for its production. The method according to the invention includes the following steps: a) coating of a mount (5a) with a non-conductive adhesive (4a); b) application of a conductor structure (3) to a subarea of the adhesive layer (4a); c) arrangement of an electronic component (1) with at least one external electrical connecting contact (2) on the adhesive layer (4a) and on the conductor structure (3), with the at least one connecting contact (2) of the electronic component (1) being brought directly into contact with the conductor structure (3), and with a part of the outer casing of the component (1) being brought directly into contact with the adhesive layer (4a). The method according to the invention allows electronic, in particular microelectronic, functional groups to be produced with care, quickly and in particular at low cost.

IPC 8 full level

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Citation (search report)

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